

EC360CARBON

Thermal Paste Series

Designed as an all-round thermal paste with the best possible price-performance ratio the EC360® CARBON series is the ideal thermal interface material for gaming PCs and industrial cooling systems. Nano-Carbon compounds blended in a base of nanometer sized metal oxide particles (silver/aluminum/boron/zinc) enable ultimate stability and a high thermal

conductivity of 5.15W/mK. Its good consistency makes it easy to spread and install. It is long-lasting: low bleed, non-flowing and low evaporation mean it will stay in place and not dry out over time. At the same time, it is not electrically conductive, which allows a safe application.

Material Composition

Type	Percentage
Metal Oxide Compounds	45%
Carbon Compounds	45%
Silicone	10%

Types and Configurations

Type*	Available sizes*
Tube	3.5 g, 20 g

* Custom configurations are available upon request, for worldwide industrial inquiries please contact us at: sales@extremecool360.com

Technical Properties

Properties	Unit	Value	Test method
Color	-	grey	Visual
Thermal Conductivity	W/mK	5.15	ASTM D5470
Thermal Resistance	°C-in²/W	0.04	ASTM D5470
Specific Gravity	g / cm³	2.5	ASTM D 792
Evaporation(150°C/24h)	%	0.001	FED STD 791
Bleed(150°C/24h)	%	0.05	FED STD 791
Viscosity	cP	12500	-
Dielectric Constant	1Mhz	5.1	ASTM D 150
Usable Temperatures	°C	-60 - 200	EN 344
Flame Rating	-	VO	UL 94

Installation Recommendation

- Clean surfaces from dirt and other possible residue. If applicable, isopropyl 90% alcohol is recommended to ensure a clean surface.
- Apply the product, for example by applying a drop in the center of the chip.
- Install the heatsink. Ideally the drop should have spread now, covering the entire chip in a thin layer of thermal paste without any air bubbles.
- If the result is not satisfactory apply again in a different quantity until the desired result has been achieved.